

ABSTRACT

WIRE SAW APPARATUS

The present invention provides a wire saw apparatus including: a wire row formed of a wire which is wound around a plurality of wire guides and reciprocatively travels in an axial direction; a nozzle from which a coolant or slurry is supplied to the wire; and a workpiece feed mechanism which presses a held workpiece against the wire row, the wire saw apparatus being configured to slice the workpiece into a wafer shape by pressing the workpiece held by the workpiece feed mechanism against the wire row and feeding it for slicing while supplying the coolant or the slurry from the nozzle to the wire, the wire saw apparatus being characterized in that the nozzle is arranged above the wire row to be orthogonal to the wire row, and windbreak plates are arranged on both left and right sides of the arranged nozzle seen from an axial direction.

Figure 1